
Cleaning and Surface Conditioning Technology in Semiconductor Device Manufacturing 10

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Table of Contents

Preface iii

Chapter 1 20 Years of Wafer Cleaning

Evolution of Silicon Cleaning Technology Over the Last Twenty Years * 3
J. Ruzyllo, T. Hattori, R. E. Novak, P. Mertens and P. Besson

Chapter 2 Cleaning Challenges for Nano-Scale Devices

Issues and Challenges of Cleaning for Nano-Scale NAND Flash Memory Manufacturing * 11
C. Ryu, Y. Song, G. Jin and S. Park

Corrosion Suppression During Wet Processes in FEOL and BEOL for 45nm Node and Beyond * 19
H. Aoki, D. Watanabe, S. Hotta, C. Kimura and T. Sugino

Chapter 3 Dry Cleaning

Yield Improvement Using Cryogenic Aerosol for BEOL Defect Removal 33
J. Lauerhaas, Y. Kok, A. Hamzah and L. Tan

Characteristics of High Power Laser Shock Waves and Their Cleaning Performance 41
T. Kim, Y. Yoo, I. Son, D. Jang, D. Kim, J. Lee, J. Choi, A. Busnaina and J. Park

Thermal Cleaning of Silicon Nitride with Fluorine and Additive Mixture 47
T. Shigemoto and J. Sonobe

Particle Removal from Micrometer-Sized Trenches Using High-Velocity-Aerosol Cleaning and Comparison with Megasonic Tank Cleaning	55
<i>K. L. Wostyn, K. Sano, A. Eitoku, T. Janssens, T. Bearda, L. Leunissen and P. Mertens</i>	

Chapter 4 Wet Etching

Maintaining a Stable Etch Selectivity between Silicon Nitride and Silicon Dioxide in a Hot Phosphoric Acid Bath	63
<i>L. Liu, I. Kashkoush, G. Chen and C. Murphy</i>	
Etching of Thermal SiO ₂ in Supercritical CO ₂	71
<i>S. Malhouitre, J. Van Hoeymissen, C. Case and P. Granger</i>	
Removal of Organic Wax and Particles on Silicon after Batch Type Polishing by Ozonated DI Water	79
<i>J. Yi, S. Lee, T. Kim, J. Park, G. Lee and S. Bae</i>	

Chapter 5 Megasonic Cleaning

Damage Clustering and Damage-Size Distributions After Megasonic Cleaning	87
<i>C. De Marco, K. L. Wostyn, T. Bearda, K. Sano, K. Kenis, T. Janssens, L. Leunissen, A. Eitoku and P. Mertens</i>	
Removal of Backside Particles by a Single Wafer Megasonic System	95
<i>H. Sohn, U. Hong, C. Park, E. Lee, H. Lee, E. Brause and J. Park</i>	
Particle Removal from Si Substrates in Organic Solvents using Megasonic Energy	101
<i>F. Barbagini, T. Janssens, T. Bearda, S. Armini, J. Van Hoeymissen, P. Mertens and J. Fransaer</i>	
Using Megasonics to Extend Chemical Cleans for 45nm Technology	109
<i>C. Franklin, Y. Fan, E. Brause and V. Nguyen</i>	
High Efficiency Wafer Backside Cleaning with Full Coverage Megasonics Spin Process	117
<i>B. Xie, S. Park, J. Han, Z. Li, R. Gouk, W. Lu, C. H. Jeon, V. Subbaraman, K. Child, J. Wright, J. Papanu and J. Tang</i>	
Quantitative Measurement of Pattern Collapse and Particle Removal Force	123
<i>T. Kim, K. L. Wostyn, P. Mertens, A. Busnaina and J. Park</i>	

Chapter 6

Metal Contamination

The Metallic Contamination Related Whisker Defect During Deposition and Its Removal *	133
<i>G. Choi</i>	
Dissemination of Metallic Contamination During IC Manufacturing	143
<i>A. Danel, Y. Borde, A. Maurel, B. Laetitia and A. Royer</i>	
Impact of Metallic Contamination on Si: Shortloop Issues	151
<i>Y. Borde, A. Maurel, A. Danel, A. Roche and M. Veillerot</i>	
Automating Metal Lift-Off for Mass MEMS Production	159
<i>J. J. Naughton and P. Franklin</i>	
A New Approach for FEOL Critical Wafer Surface Cleaning	167
<i>T. Fischer, S. Puri, R. Hoyer, K. L. Wostyn and T. Janssens</i>	

Chapter 7

Photoresist Removal

All-Wet Strip Approaches for Post-Etch Photoresist Layers After Low-K Patterning *	177
<i>M. Claes, Q. Le, E. Kesters, M. Lux, A. Urionabarrenetxea, G. Vereecke, P. Mertens, R. Carleer and P. Adriaensens</i>	
Plasma-Less Photoresist Stripping	189
<i>H. Takahashi</i>	
Wet Resist Strip Capability vs. Implant Energy	197
<i>K. K. Christenson</i>	
Single Wafer Tool Cleaning for Bi-layer Photoresist Rework - Stripper Development and Evaluation	203
<i>A. Wu, E. Baryschpolec, L. Molnar, S. Henry, S. Detterbeck, L. Brilz, C. Bartsch, G. Sulzer and A. Ott</i>	
Effect of Ashing, Strip and Annealing Process on the Dopant Concentration of Silicon	211
<i>M. Lee, I. Park, D. Kang, D. Han, Y. Son, K. Lee, C. Hong, C. Kang and J. Moon</i>	

Post Ion-Implant Photoresist Removal via Wet Chemical Cleans Combined with Physical Force Pretreatments	219
<i>G. G. Totir, M. Frank, R. Vos, S. Arnauts, T. Bearda, K. Kenis, M. Delande, Q. Le, E. Kesters, G. Vereecke, G. Mannaert, M. Lux, I. Hoflijik, T. Conard, S. Banerjee, S. Malhouitre, L. Leunissen and P. Mertens</i>	
A Review of Microelectronic Manufacturing Applications Using DMSO-Based Chemistries	227
<i>G. Kvakovszky, A. McKim and J. C. Moore</i>	
Novel Wet Photoresist Strip for Wafer Level Packaging	235
<i>S. Verhaverbeke and J. Zhao</i>	
Study of SiO ₂ Modifications Induced by Oxygen Plasmas and Their Effect on Wet Processes	239
<i>A. Votta, E. Bellandi, M. Alessandri, A. Vedda, A. Ferretti, M. Fasoli and F. Moretti</i>	

Chapter 8 Single Wafer Cleaning

Advanced Surface Preparation Development on a 300 mm Single Wafer Spin-on Platform	249
<i>G. Briend, P. Besson, T. Salvetat and O. Pollet</i>	
Gate Oxide Cleans on Single Wafer Tool	257
<i>P. Garnier, T. Vessa, A. Larrea, B. Pernet, Y. Gomez, D. Barge, A. Torres, B. Tavel, C. Henderson and D. Levy</i>	

Chapter 9 Contact Hole/Trench Cleaning

Challenges in Sub-Micron Contact Hole Cleaning	267
<i>F. Goh, T. Tjoa, K. Yeo and Z. Ismail</i>	
The Impact of Drying Methods on Defect Generation in Deep Trench Processing	275
<i>C. Goessens, N. Martens, J. Baele, E. De Backer, F. De Pestel and M. Engle</i>	
The Effect of Delay Between Dry Etch and Wet Clean Processing Steps on Cleaning of Post-Etch Residues	283
<i>D. Hellin, I. J. Vos, G. Vereecke, E. Pavel, W. Boullart and J. Vertommen</i>	

Via Failures in a Plug Process Due to Incomplete Via Clean Chemistry Removal 291
D. M. Florence, S. Burtosky, C. Cioffi, J. Doub, K. Mortensen and C. Russell

Liquid Infiltration Mechanism for Cleaning in Deep Microholes 299
K. Ota and A. Tsutsumi

Chapter 10

Front End of the Line Cleaning

Wet Etching Step Evolutions for Selective Removal on Silicide or Germanide Applications * 309
V. Carron, P. Besson and F. Pierre

Challenges in Nickel Platinum Silicide Wet Etching for Sub-65nm Device Technology 321
F. Goh, V. Sih, W. Tan and Z. Ismail

Post Salicidation Clean: Selective Removal of Un-Reacted NiPt Towards NiPtSi(Ge) 327
K. Xu, A. Lauwers, R. Vos, L. Archer, H. Kraus, C. Demeurisse, S. Mertens, S. Henry, G. Gale, P. Mertens, F. Kovacs, M. Dalmer and E. Gaulhofer

Zero Defectivity Dual Gate Processing 335
J. M. Towner, J. J. Naughton and R. Lappan

Interactions of Sapphire Surfaces with Standard Cleaning Solutions 343
K. W. Kirby, K. Shanmugasundaram, V. Bojan and J. Ruzyllo

Chapter 11

Particle Removal/Interactions

Local Removal Frequency of Nano Particles in Megasonic Cleaning 353
T. Janssens, K. L. Wostyn, S. Arnauts, A. De Geyter, T. Bearda and P. Mertens

Effect of Particle Deposition and Wet/Dry Cleaning Methods on Particle Removal Efficiency 361
T. Kim, S. Hu, A. Busnaina and J. Park

Nano Particle Control on 300mm-wafers in Supercritical Fluid Technology 369
J. Inahara, R. Okamoto, S. Kang, M. Nakahira, S. Hasegawa and T. Takahagi

Parametric Nano Particle Cleaning <i>S. Ligai, S. Pravdin and M. Ligai</i>	377
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Chapter 12 Back End of the Line Cleaning

Elimination of Post Cu-CMP Watermark by Optimizing Post CMP Clean to Control Cu Dissolution * <i>S. Petitdidier, M. Mellier, C. Trouiller, C. Euvrard and M. Juhel</i>	387
Electrochemical Behavior of Copper in Post-Via-Etch Cleaning Solutions <i>S. Bilouk, C. Pernel, R. P. Nogueira, L. Broussous, P. Haumesser and G. Passemard</i>	395
A Novel Concept for Contact Etch Residue Removal <i>I. J. Vos, D. Hellin, S. Demuynck, O. Richard, T. Conard, J. Vertommen and W. Boullart</i>	403
Modifications of Porous Low-k by Plasma Treatments and Wet Cleans <i>K. Xu, G. Vereecke, E. Kesters, Q. Le, M. Lux, S. Henry, H. Kraus, L. Archer, P. Mertens, F. Kovacs, M. Dalmer, E. Gaulhofer, S. Luo, Q. Han and I. Berry</i>	409

Chapter 13 CMP Cleaning

Surface Preparation in CMP Process; Post CMP Cleaning and Defects * <i>J. Park and T. Kim</i>	419
Post Cu-CMP Engineering Challenges for the 65 nm Technology Nodes and Beyond * <i>S. Petitdidier, M. Mellier, D. Guiheux and M. Juhel</i>	431
Post W CMP Cleaning Without HF Cleans <i>Y. Kang, C. Yang, T. Kwon, J. Park, J. Jo and G. Lim</i>	441
Incorporation of Cu Passivators in Post-CMP Cleaners <i>D. W. Peters</i>	447
Effect of Poly Silicon Wettability on Polymeric Residue Contamination <i>Y. Kang, J. Park, Y. Hong, S. Han, S. Yun, B. Yoon and C. Hong</i>	455

Chapter 14
Photomask Cleaning

Particle Adhesion to Photomask Substrates <i>R. Jaiswal, C. Kilroy, G. Kumar, S. Banerjee and S. Beaudoin</i>	465
Removal of Gold Particles from Chromium Oxynitride Surface with Dilute Sulfuric Acid Solutions <i>V. S. Pandit, M. Keswani, S. Raghavan, K. Muralidharan, P. Deymier, F. Eshbach, A. Sengupta and H. Yun</i>	471
Author Index	479

* = *invited paper*